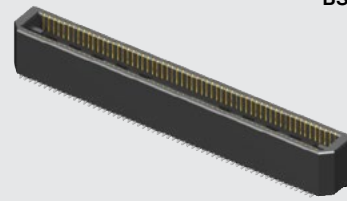


BTE-040-02-L-D-A



BTE-060-02-F-D-A

BSE-020-01-F-D-A



BTE, BSE SERIES

(0.80 mm) .0315"

BASIC BLADE & BEAM HEADER & SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?BTE or www.samtec.com?BSE

- Insulator Material:** Liquid Crystal Polymer
- Contact Material:** Phosphor Bronze
- Plating:** Au or Sn over 50 μ" (1.27 μm) Ni
- Current Rating:** 2 A per pin (2 pins powered)
- Operating Temp Range:** -55 °C to +125 °C
- Voltage Rating:** 225 VAC with 5 mm Stack Height
- Max Cycles:** 100
- RoHS Compliant:** Yes

PROCESSING

- Lead-Free Solderable:** Yes
- SMT Lead Coplanarity:** (0.10 mm) .004" max (020-080) (0.15 mm) .006" max (100-120)
- Board Stacking:** For applications requiring more than two connectors per board or 80 positions or higher, contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



MATED HEIGHT

LEAD STYLE	MATED HEIGHT*
-01	(5.00) .197
-02	(8.00) .315

*Processing conditions will affect mated height.

ALSO AVAILABLE (MOQ Required)

- 30 μ" (0.76 μm) Gold
- Edge Mount Capability
- Friction Lock option
- 11 mm, 14 mm, 16.10 mm, 19.10 mm, 22 mm, 25 mm and 30 mm Stack Height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.)

Contact Samtec.

Note: Some lengths, styles and options are non-standard, non-returnable.

BTE — **NO. OF POSITIONS PER ROW** — **LEAD STYLE** — **PLATING OPTION** — **D** — **A** — **OTHER OPTION**

Mates with: **BSE**

-020, -040, -060, -080, -100, -120

Specify LEAD STYLE from chart

LEAD STYLE	A
-01	(4.27) .168
-02	(7.21) .284

-F = Gold Flash on contact, Matte Tin on tail

-L = 10 μ" (0.25 μm) Gold on contact, Matte Tin on tail

-C* = Electro-Polished Selective 50 μ" (1.27 μm) min Au over 150 μ" (3.81 μm) Ni on Signal Pins in contact area, Matte Tin over 50 μ" (1.27 μm) min Ni on all solder tails

*Note: -C Plating passes 10 year MFG testing

-K = (7.00 mm) .275" DIA Polyimide Film Pick & Place Pad

-TR = Tape & Reel (80 positions maximum)

POWER/SIGNAL APPLICATION



Compatible with UMPT/UMPS for flexible two-piece power/signal solutions

BSE — **NO. OF POSITIONS PER ROW** — **01** — **PLATING OPTION** — **D** — **A** — **OTHER OPTION**

Mates with: **BTE**

-020, -040, -060, -080, -100, -120

-F = Gold Flash on contact, Matte Tin on tail

-L = 10 μ" (0.25 μm) Gold on contact, Matte Tin on tail

-C* = Electro-Polished Selective 50 μ" (1.27 μm) min Au over 150 μ" (3.81 μm) Ni on Signal Pins in contact area, Matte Tin over 50 μ" (1.27 μm) min Ni on all solder tails

*Note: -C Plating passes 10 year MFG testing

-TR = Tape & Reel (80 positions maximum)

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications. Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.